

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 1309 | "resin composition" and epoxy and phenolic and accelerator and filler and viscositY | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:09 |
| L2 | 28 | 1 and viscosity with poise with (room "25") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:09 |
| L3 | 2 | jp-02147618-\$.did. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:09 |
| L4 | 1 | 1990-219830.NRAN. | DERWENT | OR | ON | 2005/11/10 17:09 |
| L5 | 14 | ("6215180").URPN. | USPAT | OR | ON | 2005/11/10 17:10 |
| L6 | 2 | jp-10189832-\$.did. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:10 |
| L7 | 6 | epoxY with resin with temperature with viscosity with temperature with dependency | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:10 |
| L8 | 5542 | (257/79\$1).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/10 17:10 |
| L9 | 54 | 8 and viscosity with poise | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:10 |
| L10 | 893 | (257/788).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/10 17:11 |

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|-----|------|--|---|----|-----|------------------|
| L11 | 3701 | (257/787).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/10 17:11 |
| L13 | 4335 | 10 11 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:11 |
| L14 | 43 | 13 and viscosity with poise | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:17 |
| L15 | 9160 | 8 OR 13 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:12 |
| L16 | 10 | 15 AND epoxy with phenolic with curing adj accelerator with inorganic adj filler | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:12 |
| L17 | 2980 | semiconductor with resin and resin with viscosity | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:12 |
| L19 | 301 | accelerator with core with (shell coat coating layer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:13 |
| L20 | 54 | epoxy with phenolic with curing adj accelerator with inorganic adj filler | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/10 17:13 |
| L21 | 3 | 19 and 20 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/10 17:15 |